FEATURES

Wafer Frame Handling

- Programmable film expansion
- Automatic wafer frame changer
- UV cure station

Pick and Place

- Device size 0.5 to 10 mm
- Placement Accuracy 0.025 mm
- High Speed: 8000uph to tape and reel with flipping
- Synchronized Ejector with pick and place head reduce stress on die
- Retractable Flipper to allow option of not flipping the device
- Vision Guided Pick and Place System. Device and pocket are located by vision prior to placement into pocket

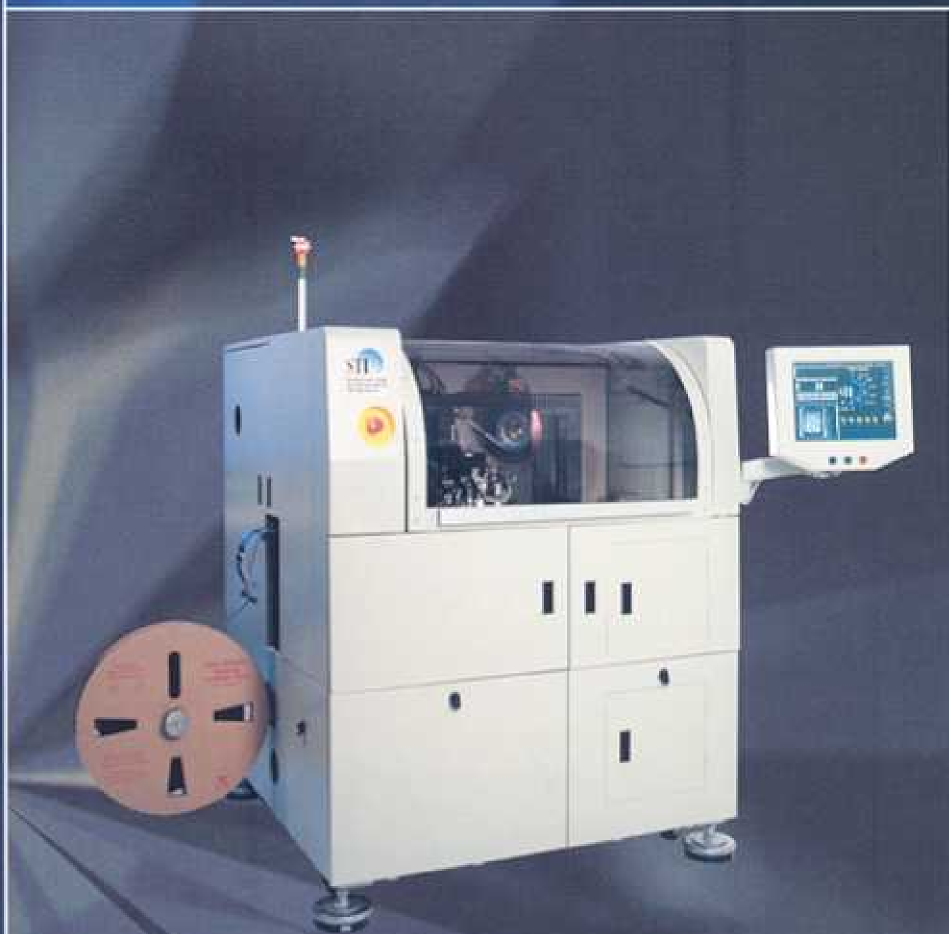
Tape and Reel

- Tape Width 8 to 24 mm
- Auto Reject Management. Inspected device inside the tape pocket that failed inspection is automatically replaced with good unit
- Empty Pocket Detection. When an empty pocket is detected, carrier tape will be reversed and a good unit will be replenished
- Unit out of pocket detection is achieved by vision system after placement
- Programmable Sealing Parameters (i.e. pressure, temperature and time)

Tray Handling System (Optional)

- Manual or Automatic
- Tray type: JEDEC, Waffle and Gel Pak.

SEMICONDUCTOR
TECHNOLOGIES
& INSTRUMENTS



*i*SORT

*i*ntelligent, *i*ntuitive and *i*ncredibly fast die sorters

*i*SORT is an intelligient die sorter which sorts dies into tape and reel at high speed. Adopting STI's proprietary vision technology, *i*SORT inspects and sorts wafer level chip scale packages into tape and reel. The intelligent vision capability ensures that only quality devices are picked and placed into tape and reel using a special vision guided Pick and Place System.

*i*SORT SPECIFICATIONS

USER INTERFACE

- Wafer mapping of complex arrays and matrix strips
- Networking (SECS/GEM)
- Window NT platform with GUI
- Touch Screen Monitor
- Intuitive and user friendly software
- Full Machine diagnostics capability

FACILITY

Footprint	: 1.66m x 1.28m x 1.67m
Weight	: 1600 kg
Electrical	: 240 VAC, 50/60 Hz 20 Amp or 110 VAC, 50/60 Hz 40 Amp.
Air	: 100 liter/min @ 5 bar

TOP SIDE (IN-POCKET) INSPECTION

- Inspect marking
- Customer logo
- Blurred mark
- Scratches
- Mixed devices
- Angled mark
- Crack device
- Voids/incomplete fill
- Edge chip off
- Contamination
- Scratches

BOTTOM (ACTIVE DIE) INSPECTION

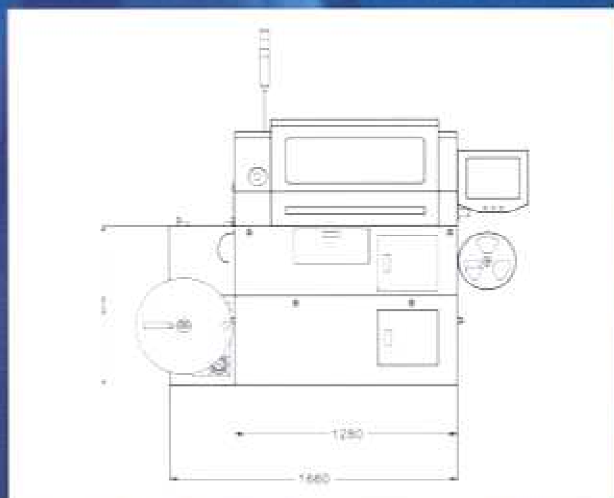
Measure

- Package dimension
- Pad/ball offset
- Pad/ball size
- Pad/ball pitch
- Device edge and pad dimension

Inspect

- Ink dot reject
- Crack
- Edge Chip Off
- Scratches
- Contamination
- Part presence

*i*SORT DIMENSIONS



Semiconductor Technologies & Instruments Pte Ltd

Blk 25, Kallang Ave #06-01, Kallang Basin Industrial Estate, Singapore 339416.
Tel: 6392 6922 Fax: 6392 6933 Email: marketinggp@stigp.com URL: www.stigp.com

All specifications are subjected to change without notice inorder to improve machine capabilities and functions